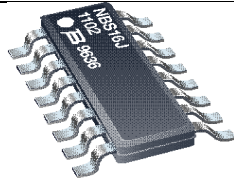


MATERIAL DECLARATION SHEET



Reliable Electronic Solutions

Material #	CDNBS16 Series	
Product Line	Integrated Passive & Active Devices	
Date	5/27/2004	
RoHS Compliant	Yes	

COMPONENT DETAILS

No.	Construction element	Material group	Material weight [g]	Materials	CAS if applicable	Average mass [%]	Sum [%]	Traces
1	Lead Frame	Lead Frame	0.0757	Cu	7440-50-8	48.23	50.87	
				Ni	7440-02-0	0		
				Sn	7440-31-5	2.447		
2	Wafer	Silicon	0.01434	Silicon	7440-21-3	9.444	9.637	
				Other material		.1927		
3	Gold Bond wire	Conductor	0.000352	Au	7440-57-5	.2352	.2365	
				SI		.0023		
4	Silver paste	Die Attach	0.000808	Ag	7440-22-4	.4235	.5430	
				Epoxy		.1195		
5	Molding Component	Outer	0.0576	Silica fused	60676-86-0	32.90	38.71	
				Epoxy resin	68928-70-1	3.871		
				Phenol resin	29690-82-2	2.322		
Total weight			0.1488					

Pb Free Part Number Example: CDNBS16-T05C

Note: Avg. mass and sum data is a % of the component weight.
It is the responsibility of the user to ensure that the latest revision is being accessed on the website.